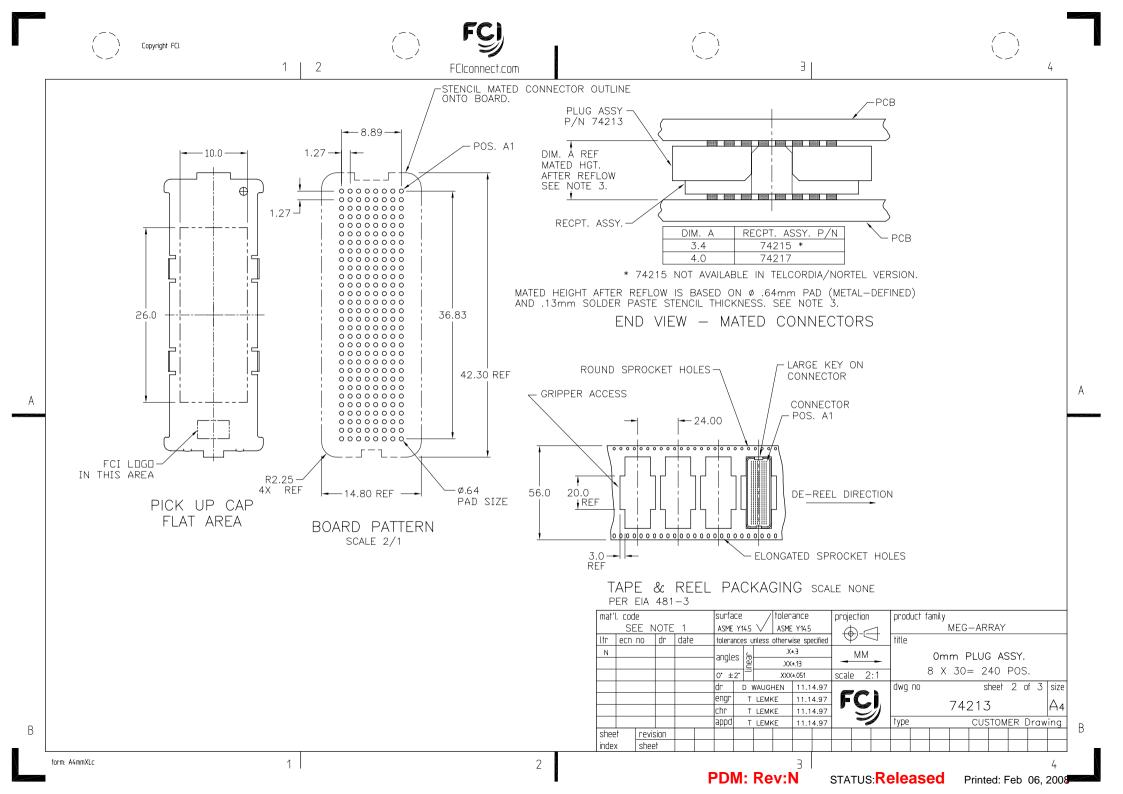


PDM: Rev:N

STATUS: Released

Printed: Feb 06, 2008



1 | 2

FCIconnect.com

3 |

NOTES:

1.)<sub>MAT</sub>'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Aa/0.5Cu

- (2.)SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- 3.)MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE. PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (5.) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (6) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

1

mat'l. code							surface / tolerance					projection product family											
SEE NOTE 1						ASME Y14.5 V ASME Y14.5						\$.□			MEG-ARRAY								
ltr	ecn no dr date				tolerances unless otherwise spec					ecified				title									
N						angle	ے اے	.X:		±.3		ММ			0mm PLUG ASSY.								
						anyte	s Pa	.XX±.13				-											
						0° ±2°		.XXX±.051				scale	2	::1	8 X 30= 240 POS.								
						dr	D١	D WAUGHEN		11.14.97					dwg	no			S	heet	3 (	of 3	size
							Т	LEMKE		11.14.97		FCi				74017							
						chr		LEMKE		11.14.97				74213 A						A4			
						appd	Т	LEMKE		11.14.97					type	type CUSTOMER Drawing							ing
she	et	revis	sion																				
index		sheet																					
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PDM: Rev:N